Application Data Sheet

Application Information

Application Type:: Regular

Subject Matter:: Utility

Suggested Classification::

Suggested Group Art Unit::

CD-ROM or CD_R?:: Table

Number of CD disks::

Number of copies of CDs::

Sequence Submission:: No

Computer Readable Form (CRF)?:: No

Title:: METHOD OF FABRICATING A MULTI-LAYER

CIRCUIT BOARD ASSEMBLY

Attorney Docket Number:: 8688.258US01

Request For Early Publication:: No

Request For Non-Publication:: No

Suggested Drawing Figure::

Total Drawing Sheets:: 3

Small Entity:: No

Latin Name::

Variety Denomination Name::

Petition Included:: No

Petition Type::

Licensed US Govt. Agency::

Contract or Grant Numbers::

Secrecy Order in Parent Appl.?:: No

Applicant Information

Applicant Authority Type::

Inventor

Primary Citizenship::

Taiwan

Country::

Taiwan

Status::

Full Capacity

Given Name::

Yu-Chiang

Middle Name::

Family Name::

CHENG

Name Suffix::

City of Residence::

Taipei City

State or Province of Residence::

Country of Residence::

Taiwan

Street of mailing address::

3F, No. 17, Alley 5, Lane 257, Kung-Kuan Rd.,

Pei-Tou Dist.

City of mailing address::

Taipei City

State or Province of mailing address::

Country of mailing address::

Taiwan

Postal or Zip Code of mailing address::

Applicant Information

Applicant Authority Type::

Inventor

Primary Citizenship::

Taiwan

Country::

Taiwan

Status::

Full Capacity

Given Name::

Jong-Kuei

Middle Name::

Family Name::

CHEN

Name Suffix:

City of Residence::

Hua-Lien Hsien

Initial 01/15/02

 State or Province of Residence::

Country of Residence::

Taiwan

Street of mailing address::

No. 54, Chu-Tien Tsun, Fu-Li Hsiang

City of mailing address::

Hua-Lien Hsien

State or Province of mailing address::

Country of mailing address::

Taiwan

Postal or Zip Code of mailing address::

Correspondence Information

Correspondence Customer Number::

23552

Representative Information

Representative Customer Number::

23552

Assignee Information

Assignee Name::

Mitac International Corp.

Street of mailing address::

No. 1, R & D 2nd Rd., Science-Based Industrial

Park

City of mailing address::

Hsinchu Hsien

State or Province of mailing address::

Country of mailing address::

Taiwan

Postal or Zip Code of mailing address::